

Noninverting 3-State Buffer

MC74VHC1G125, MC74VHC1GT125

The MC74VHC1G125 / MC74VHC1GT125 is a single non-inverting 3-state buffer in tiny footprint packages. The MC74VHC1G125 has CMOS-level input thresholds while the MC74VHC1GT125 has TTL-level input thresholds.

The internal circuit is composed of three stages, including a buffered 3-state output which provides high noise immunity and stable output.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. Some output structures also provide protection when $V_{CC} = 0$ V and when the output voltage exceeds V_{CC} . These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

Features

- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 3.5 ns t_{PD} at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, SC-74A, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

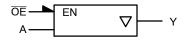


Figure 1. Logic Symbol

MARKING DIAGRAMS



SC-88A DF SUFFIX CASE 419A





SC-74A DBV SUFFIX CASE 318BQ





SOT-953 P5 SUFFIX CASE 527AE





UDFN6 1.45 x 1.0 CASE 517AQ





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.0 x 1.0 CASE 517BX



XX = Specific Device Code

M = Date Code*

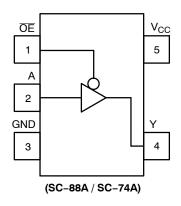
= Pb-Free Package

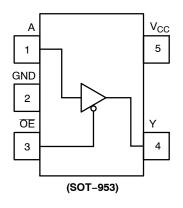
(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 8 of this data sheet.





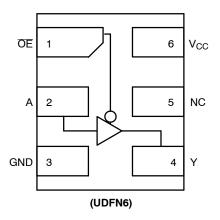


Figure 2. Pinout (Top View)

PIN ASSIGNMENT (SC-88A / SC-74A)

Pin	Function
1	ŌĒ
2	А
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	А
2	GND
3	ŌĒ
4	Y
5	V _{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	ŌĒ
2	Α
3	GND
4	Υ
5	NC
6	V _{CC}

FUNCTION TABLE

Inp	Output	
ŌĒ	Α	Υ
L	L	L
L	Н	Н
Н	Х	Z

X = Don't Care

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +6.5	V
V _{IN}	DC Input Voltage		-0.5 to +6.5	V
V _{OUT}	Tri-	e (High or Low State) -State Mode (Note 1) vn Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-20	mA
I _{OUT}	DC Output Source/Sink Current		±25	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin		±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 secs		260	°C
TJ	Junction Temperature Under Bias		+150	°C
θЈА	Thermal Resistance (Note 2)	SC-88A SC-74A SOT-553 SOT-953 UDFN6	377 320 324 254 154	°C/W
P _D	Power Dissipation in Still Air	SC-88A SC-74A SOT-553 SOT-953 UDFN6	332 390 386 491 812	mW
MSL	Moisture Sensitivity		Level 1	_
F _R	Flammability Rating Ox	ygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model narged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri–stated.

Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

^{4.} Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Char	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage		2.0	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	V
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$ $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (MC74VHC1G125)

		Test	Vcc	7	_ _A = 25°	C	-40°C ≤ 7	Γ _A ≤ 85°C	-55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	High-Level Input		2.0	1.5	-	-	1.5	-	1.5	-	V
	Voltage		3.0	2.1	-	-	2.1	-	2.1	-	
			4.5	3.15	-	_	3.15	-	3.15	-	1
			5.5	3.85	-	-	3.85	-	3.85	-	
V_{IL}	Low-Level Input		2.0	-	-	0.5	-	0.5	-	0.5	V
	Voltage		3.0	-	-	0.9	-	0.9	-	0.9	
			4.5	-	-	1.35	-	1.35	-	1.35	
			5.5	-	-	1.65	-	1.65	-	1.65	
V _{OH}	High-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -4 m\text{A} \\ &I_{OH} = -8 m\text{A} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	1.9 2.9 4.4 2.58 3.94	2.0 3.0 4.5 –	- - -	1.9 2.9 4.4 2.48 3.80	- - - -	1.9 2.9 4.4 2.34 3.66	- - - -	V
V _{OL}	Low-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	- - - -	0.0 0.0 0.0 - -	0.1 0.1 0.1 0.36 0.36	- - - -	0.1 0.1 0.1 0.44 0.44	- - - -	0.1 0.1 0.1 0.52 0.52	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	2.0 to 5.5	-	-	±0.1	-	±1.0	-	±1.0	μΑ
l _{OZ}	3-State Output Leakage Current	V _{OUT} = 0 V to 5.5 V	5.5	_	-	±0.25	-	±2.5	_	±2.5	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0.0	_	-	1.0	-	10	_	10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	-	-	1.0	-	20	_	40	μΑ

DC ELECTRICAL CHARACTERISTICS (MC74VHC1GT125)

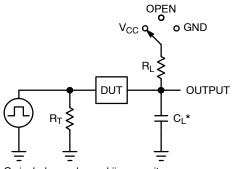
_		Test	V _{CC}	1	T _A = 25°	С	-40°C ≤	Γ _A ≤ 85°C	-55°C ≤ T	_ _A ≤ 125°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	High-Level Input		2.0	1.0	_	-	1.0	_	1.0	-	V
	Voltage		3.0	1.4	-	-	1.4	-	1.4	-	1
			4.5	2.0	-	-	2.0	-	2.0	-	
			5.5	2.0	-	-	2.0	-	2.0	-	
V_{IL}	Low-Level Input		2.0	-	-	0.28	-	0.28	-	0.28	V
	Voltage		3.0	-	-	0.45	=	0.45	-	0.45]
			4.5	-	-	0.8	-	0.8	-	0.8]
			5.5	-	-	0.8	_	0.8	-	0.8	
V _{OH}	High-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -50 \mu\text{A} \\ &I_{OH} = -4 m\text{A} \\ &I_{OH} = -8 m\text{A} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	1.9 2.9 4.4 2.58 3.94	2.0 3.0 4.5 –	- - - -	1.9 2.9 4.4 2.48 3.80	- - - -	1.9 2.9 4.4 2.34 3.66	- - - -	V
V _{OL}	Low-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 50 \mu\text{A} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	- - - -	0.0 0.0 0.0 - -	0.1 0.1 0.1 0.36 0.36	1 1 1 1	0.1 0.1 0.1 0.44 0.44	- - - -	0.1 0.1 0.1 0.52 0.52	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	2.0 to 5.5	-	-	±0.1	-	±1.0	-	±1.0	μΑ
I _{OZ}	3-State Output Leakage Current	V _{OUT} = 0 V to 5.5 V	5.5	_	_	±0.25	-	±2.5	-	±2.5	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	-	10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	_	_	1.0	-	20	_	40	μΑ
I _{CCT}	Increase in Quiescent Supply Current per Input Pin	One Input: V _{IN} = 3.4 V; Other Input at V _{CC} or GND	5.5	-	-	1.35	ı	1.5	-	1.65	mA

AC ELECTRICAL CHARACTERISTICS

				Т	A = 25°	С	-40°C ≤ 7	Γ _A ≤ 85°C	-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	C _L = 15 pF	3.0 to 3.6	_	4.5	8.0	-	9.5	_	12.0	ns
t _{PHL}	A to Y (Figures 3 and 4)	C _L = 50 pF		_	6.4	11.5	-	13.0	-	16.0	
	,	C _L = 15 pF	4.5 to 5.5	-	3.5	5.5	-	6.5	-	8.5	
		C _L = 50 pF		_	4.5	7.5	-	8.5	_	10.5	
t _{PZL} ,	Output Enable	C _L = 15 pF	3.0 to 3.6	-	4.5	8.0	-	9.5	-	11.5	ns
t _{PZH}	Time, OE to Y (Figures 3 and 4)	C _L = 50 pF		_	6.4	11.5	-	13.0	_	15.0	
	,	C _L = 15 pF	4.5 to 5.5	-	3.5	5.1	-	6.0	_	8.5	
		C _L = 50 pF		_	4.5	7.1	-	8.0	_	10.5	
t _{PLZ} ,	Output Disable	C _L = 15 pF	3.0 to 3.6	-	6.5	9.7	-	11.5	-	14.5	ns
t _{PHZ}	Time, OE to Y (Figures 3 and 4)	C _L = 50 pF		_	8.0	13.2	-	15.0	-	18.0	
	,	C _L = 15 pF	4.5 to 5.5	_	4.8	6.8	-	8.0	_	10.0	
		C _L = 50 pF		_	7.0	8.8	-	10.0	-	12.0	
C _{IN}	Input Capacitance			-	4.0	10	-	10	-	10	pF
C _{OUT}	Output Capacitance	Output in High Impedance State		-	6.0	-	-	-	-	-	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C _{PD}	Power Dissipation Capacitance (Note 5)	8.0	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



Test	Switch Position	C _L , pF	R_L, Ω
t _{PLH} / t _{PHL}	Open	See AC Characteristics Table	Х
t _{PLZ} / t _{PZL}	V _{CC}		1 k
t _{PHZ} / t _{PZH}	GND		1 k

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



Figure 4. Switching Waveforms

		V _m		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}	V _Y , V
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	0.3

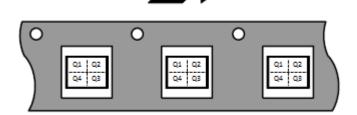
ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
MC74VHC1G125DFT1G (Contact onsemi)	SC-88A	W0	Q2	3000 / Tape & Reel
MC74VHC1G125DFT2G (Contact onsemi)	SC-88A	W0	Q4	3000 / Tape & Reel
MC74VHC1G125DFT1G-Q (Contact onsemi)	SC-88A	W0	Q2	3000 / Tape & Reel
MC74VHC1GT125DFT1G (Contact onsemi)	SC-88A	W1	Q2	3000 / Tape & Reel
MC74VHC1GT125DFT2G (Contact onsemi)	SC-88A	W1	Q4	3000 / Tape & Reel
MC74VHC1GT125DFT1G-Q (Contact onsemi)	SC-88A	W1	Q2	3000 / Tape & Reel
MC74VHC1GT125DFT2G-Q (Contact onsemi)	SC-88A	W1	Q4	3000 / Tape & Reel
MC74VHC1G125DBVT1G	SC-74A	W0	Q4	3000 / Tape & Reel
MC74VHC1GT125DBVT1G	SC-74A	W1	Q4	3000 / Tape & Reel
MC74VHC1G125P5T5G	SOT-953	Т	Q2	8000 / Tape & Reel
MC74VHC1GT125P5T5G (Contact onsemi)	SOT-953	TBD	Q2	8000 / Tape & Reel
MC74VHC1G125MU1TCG (Contact onsemi)	UDFN6, 1.45 x 1.0, 0.5P	TBD	Q4	3000 / Tape & Reel
MC74VHC1GT125MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	D	Q4	3000 / Tape & Reel
MC74VHC1GT125MU2TCG	UDFN6, 1.2 x 1.0, 0.4P	7	Q4	3000 / Tape & Reel
MC74VHC1G125MU3TCG (Contact onsemi)	UDFN6, 1.0 x 1.0, 0.35P	TBD	Q4	3000 / Tape & Reel
MC74VHC1GT125MU3TCG	UDFN6, 1.0 x 1.0, 0.35P	L	Q4	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

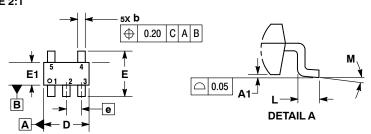
Direction of Feed

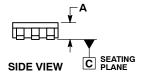


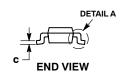
^{*-}Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



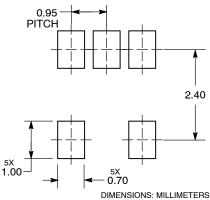
DATE 18 JAN 2018







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

	MILLIMETERS		
DIM	MIN MAX		
Α	0.90	1.10	
A1	0.01	0.10	
b	0.25	0.50	
С	0.10 0.26		
D	2.85	3.15	
E	2.50 3.00		
E1	1.35 1.65		
е	0.95 BSC		
L	0.20	0.60	
М	0° 10°		

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON66279G	Electronic versions are uncontrolled except when accessed directly from the Document Reposit Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SC-74A		PAGE 1 OF 1

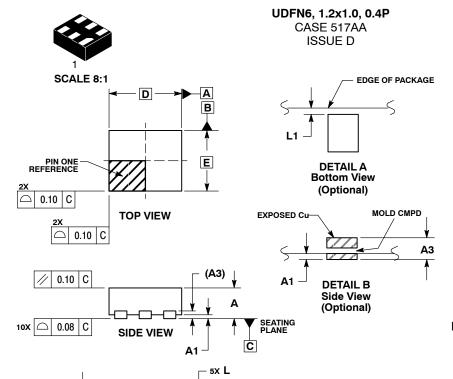
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6X b

0.10 C A B

0.05 C NOTE 3





е

BOTTOM VIEW

DATE 03 SEP 2010

NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME Y14 5M 1994
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

_	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
A3	0.127	REF	
b	0.15 0.25		
D	1.20 BSC		
E	1.00 BSC		
е	0.40 BSC		
L	0.30	0.40	
L1	0.00	0.15	
L2	0.40 0.50		

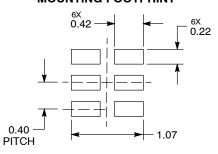
GENERIC MARKING DIAGRAM*



X = Specific Device CodeM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

MOUNTING FOOTPRINT*



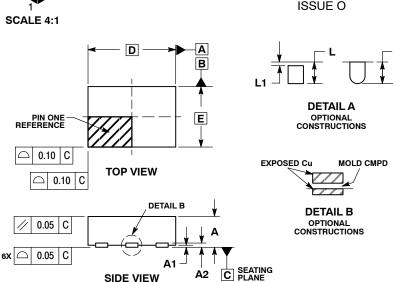
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON22068D	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	6 PIN UDFN, 1.2X1.0, 0.4P		PAGE 1 OF 1

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6X L

6X b

0.10 | C | A | B

0.05 C NOTE 3

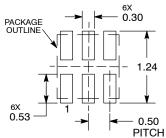
UDFN6, 1.45x1.0, 0.5P CASE 517AQ

DATE 15 MAY 2008

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00	0.05	
A2	0.07	REF	
b	0.20 0.30		
D	1.45 BSC		
E	1.00 BSC		
е	0.50 BSC		
Ĺ	0.30	0.40	
L1	0.15		

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW



= Specific Device Code

= Date Code

е

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	UDFN6, 1.45x1.0, 0.5P		PAGE 1 OF 1

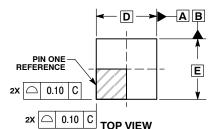
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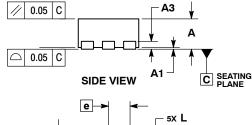


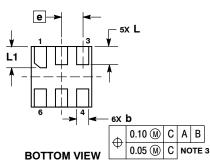


UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

DATE 18 MAY 2011





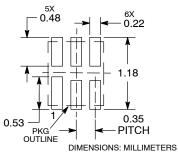


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. PACKAGE DIMENSIONS EXCLUSIVE OF
- BURRS AND MOLD FLASH.

	MILLIMETERS		
DIM	MIN MAX		
Α	0.45	0.55	
A1	0.00	0.05	
A3	0.13 REF		
b	0.12 0.22		
D	1.00 BSC		
E	1.00 BSC		
е	0.35 BSC		
L	0.25	0.35	
L1	0.30	0.40	

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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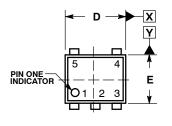
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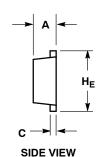
SOT-953 CASE 527AE **ISSUE E**

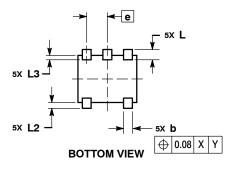
DATE 02 AUG 2011



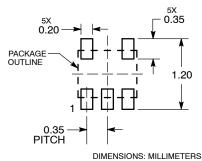


TOP VIEW





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.34	0.37	0.40
b	0.10	0.15	0.20
С	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
е	0.35 BSC		
HE	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3			0.15

GENERIC MARKING DIAGRAM*



= Specific Device Code = Month Code

*This information is generic. Please refer to device data sheet for actual part marking.

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